Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HPE Edgeline EL4000

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	
Batteries	All types including standard alkaline and lithium coin or button style batteries yes	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries NO	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps NO	0
Cathode Ray Tubes (CRT)	NO	0
Capacitors / condensers (Containing PCB/PCT)	NO	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depending on Power Supply Model	3
External electrical cables and cords		
Gas Discharge Lamps	NO	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	NO	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. NO	0

HPE instructions for this template are available at MF877-01

Item Description	Notes	Quantity of items included in product
Components and waste containing asbestos	NO	0
Components, parts and materials containing refractory ceramic fibers	NO	0
Components, parts and materials containing radioactive substances	NO	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T10& T15

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System battery: Press the latch of battery holder and pull-out the battery
2. 800 PSU Capacitor remove – See attachment 3 for cap locations.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

Attachment 1 – System exploding drawing

Attachment 2 – System battery location

Attachment 3 –800W PSU capacitor location

Attachment 4 –Remove PCI-E module

Attachment 5 – Remove the Rear module

Attachment 6 – Remove the Fan module

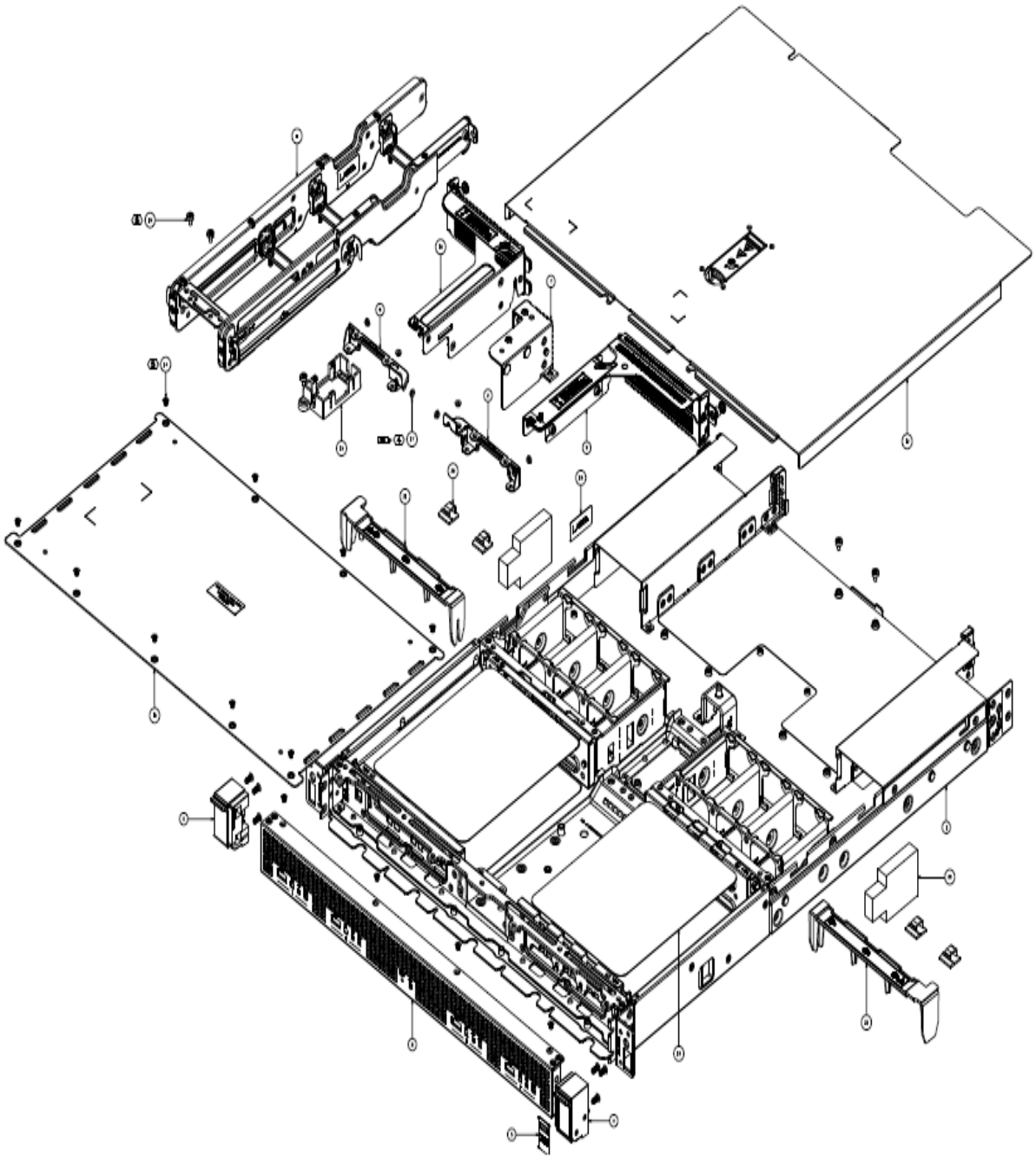
Attachment 7 – Remove the Rail module

Attachment 8 –Remove front bezel module

Attachment 9 – Remove Mainboard

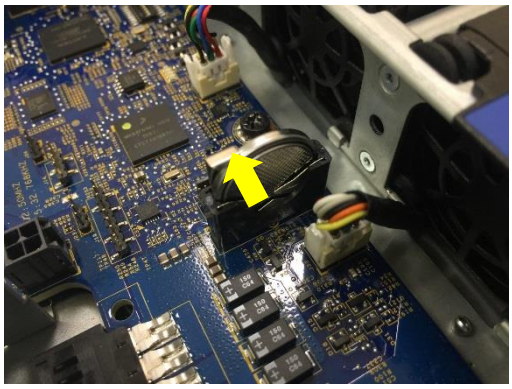
Attachment 10 – Remove800W PSU

Attachment 1 – System exploding drawing
System exploding drawing



Attachment 2 – System battery location

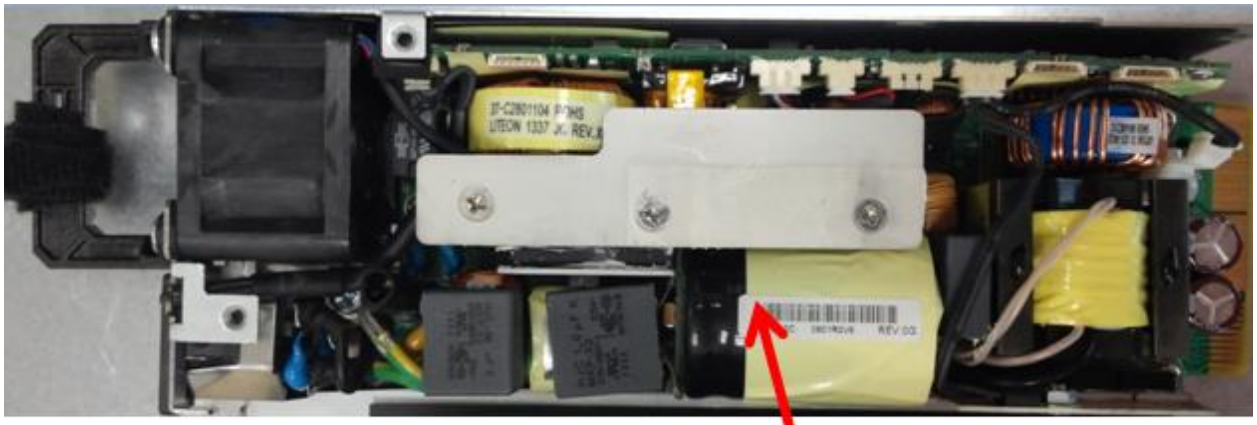
System Battery Location



Attachment 3 –800W PSU capacitor location

800W PSU capacitor location

1. Remove Caps

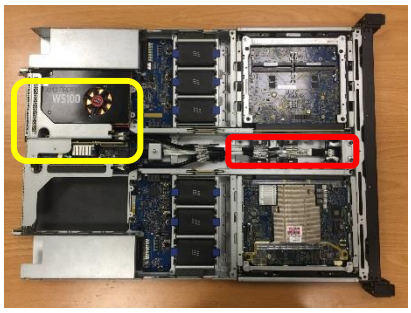


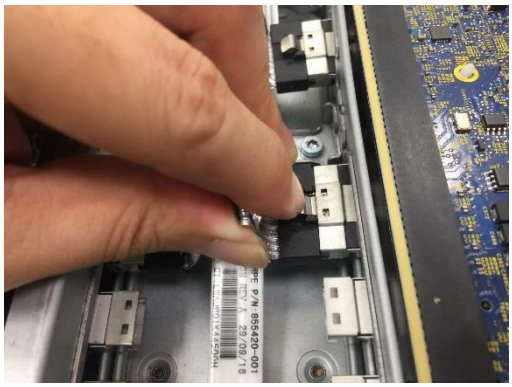
Model: HSTNS-PL41
Remove capacitor

Model: HSTNS-PD41
Remove capacitor

Remove PCI-E module

Remove Right side module



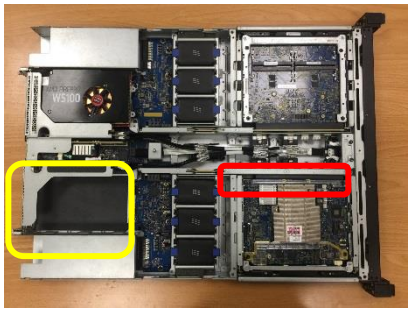


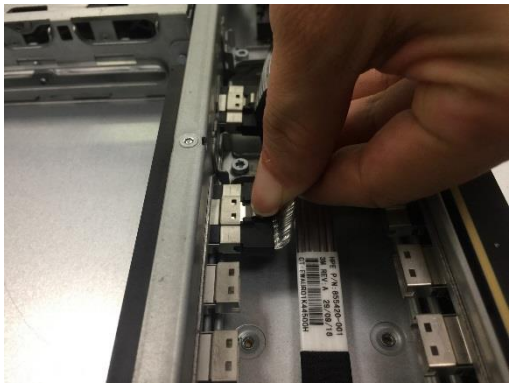
Press the latch of cable to release cable form connector (location as red remark)

Loosen the screw of PCIE module rear side by T15 screw driver

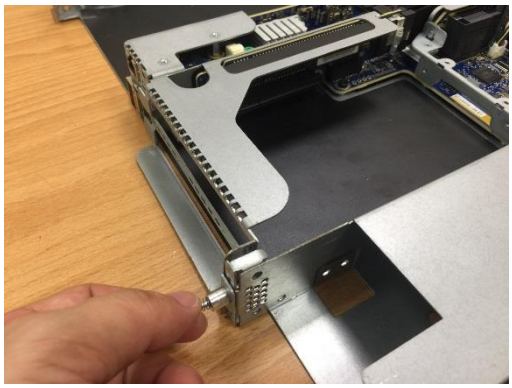
Take-out the PCI-E module form the chassis after loosening screws

Remove left side PCI-E module

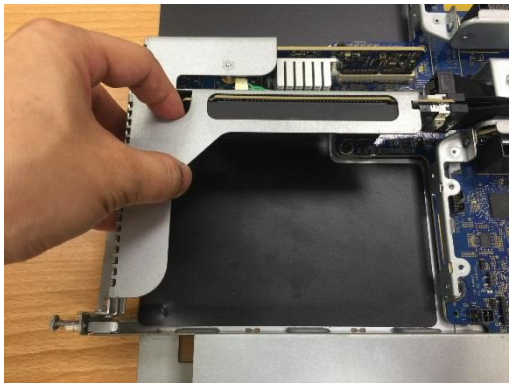




Press the latch of cable to release cable form connector (location as red mark show)

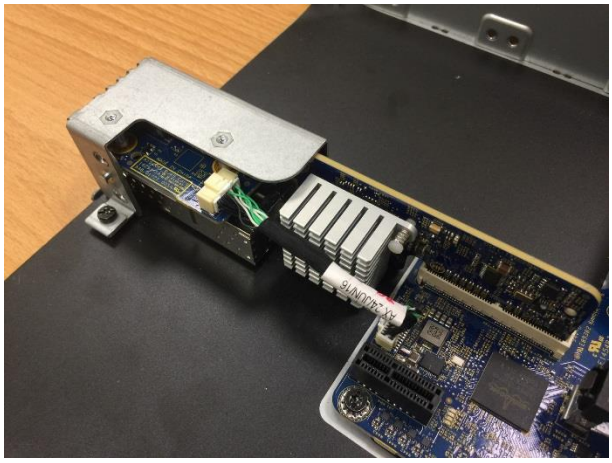


Loosen the screw of PCIE module rear side by T15 screw driver

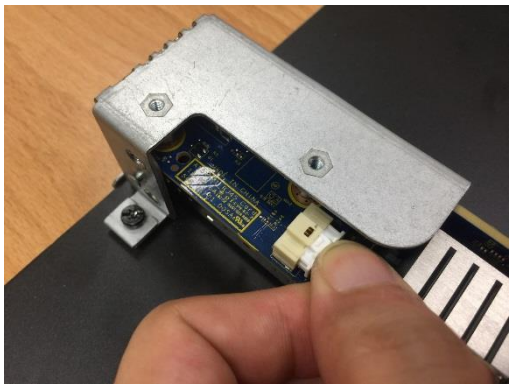
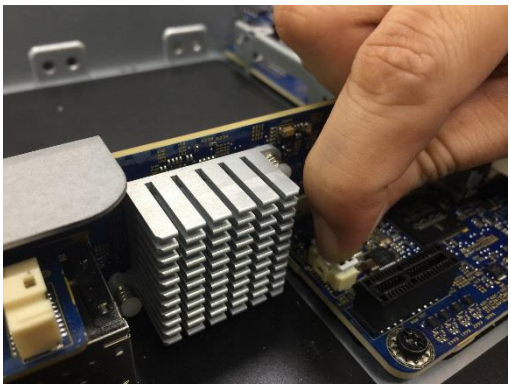


Take-out the PCI-E module form the chassis after loosening screws

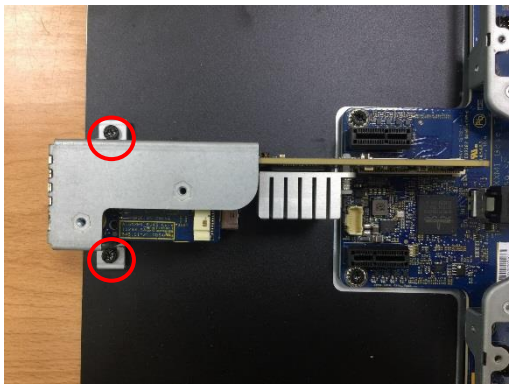
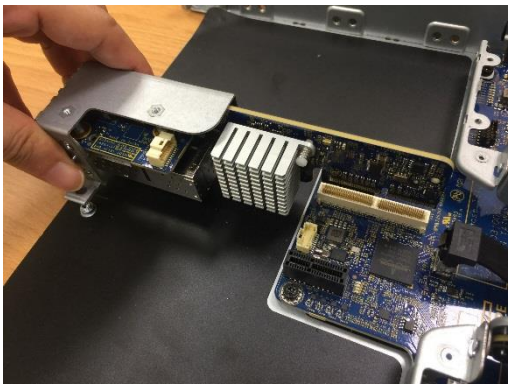
Remove the rear module



Rear module

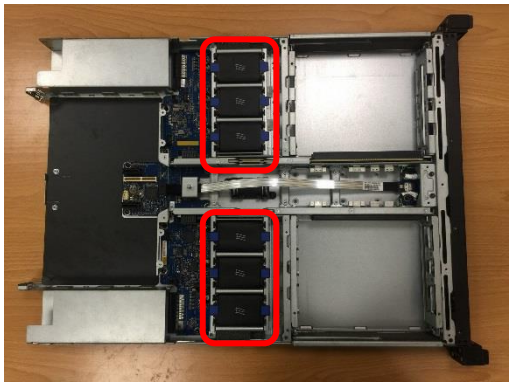



Press the latch of cable connector and release the cable from connector of board on both side to remove cable.

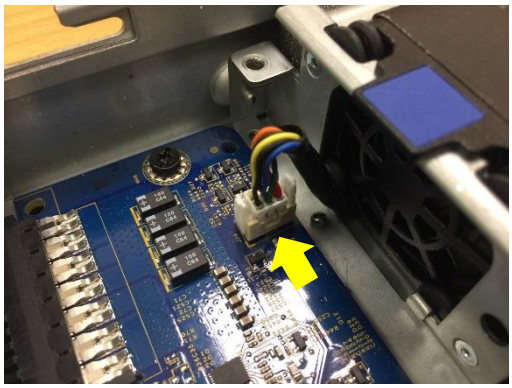



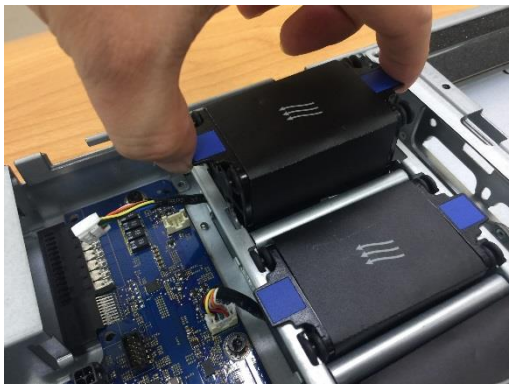
Loosen screws on rear module by T15 screw driver (totally 2pcs as red mark show) and then remove rear module from chassis.

Remove the Fan module



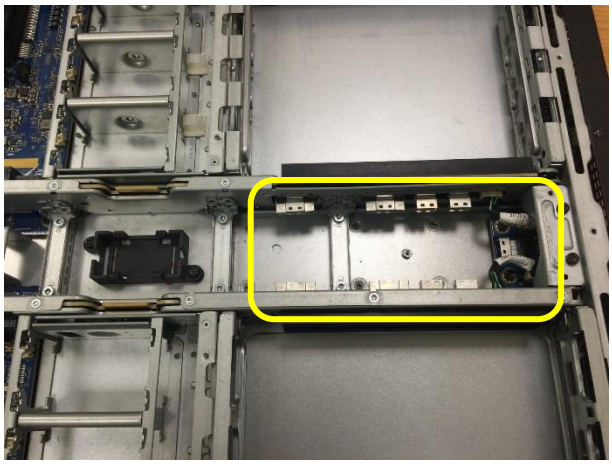
Fan module location

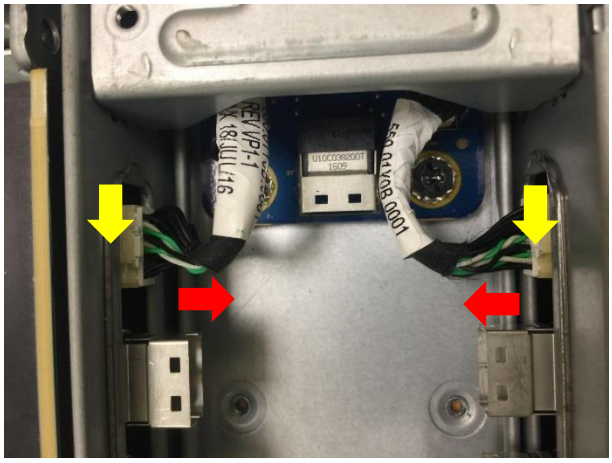




Press the latch of fan cable connector and release the cable from connector of board. Take-out the fan module from chassis after loosening all cables (Totally 6pcs)

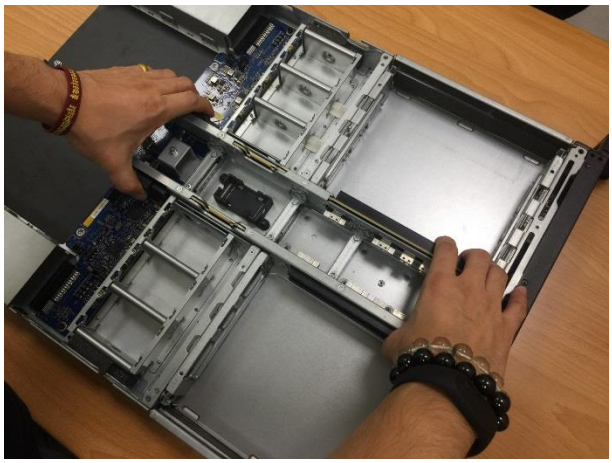
Remove the Rail module





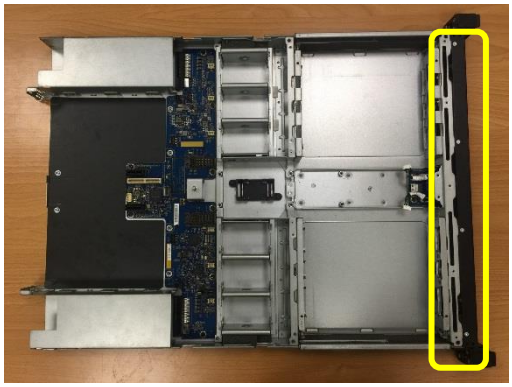
Press the latch of cable connector first (as yellow arrow direction show) and pull-up the cable from connector of rail board to release (as red arrow direction show)

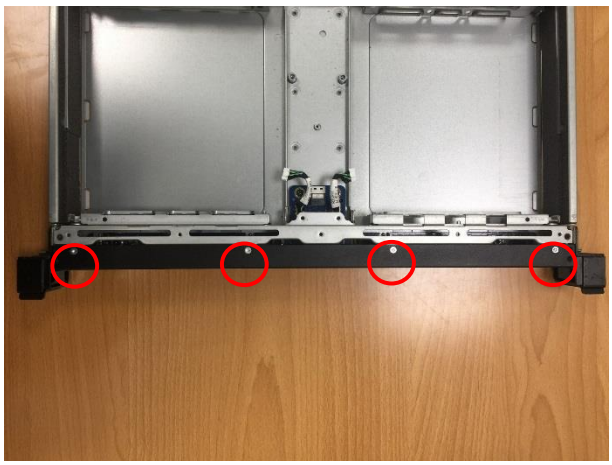
Release the other side cable by the same way



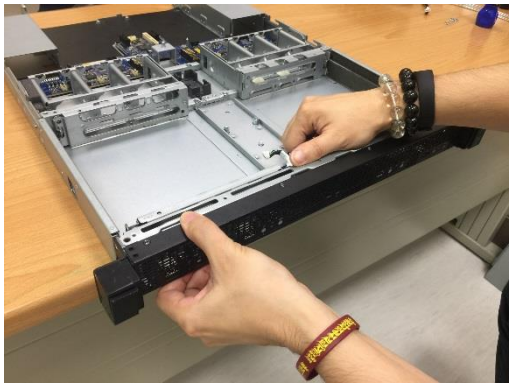
Pull-up and remove the rail module from chassis

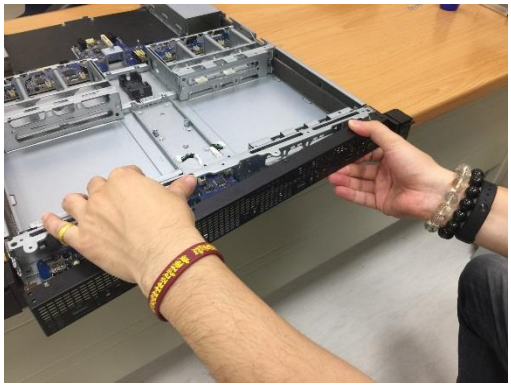
Remove front bezel module





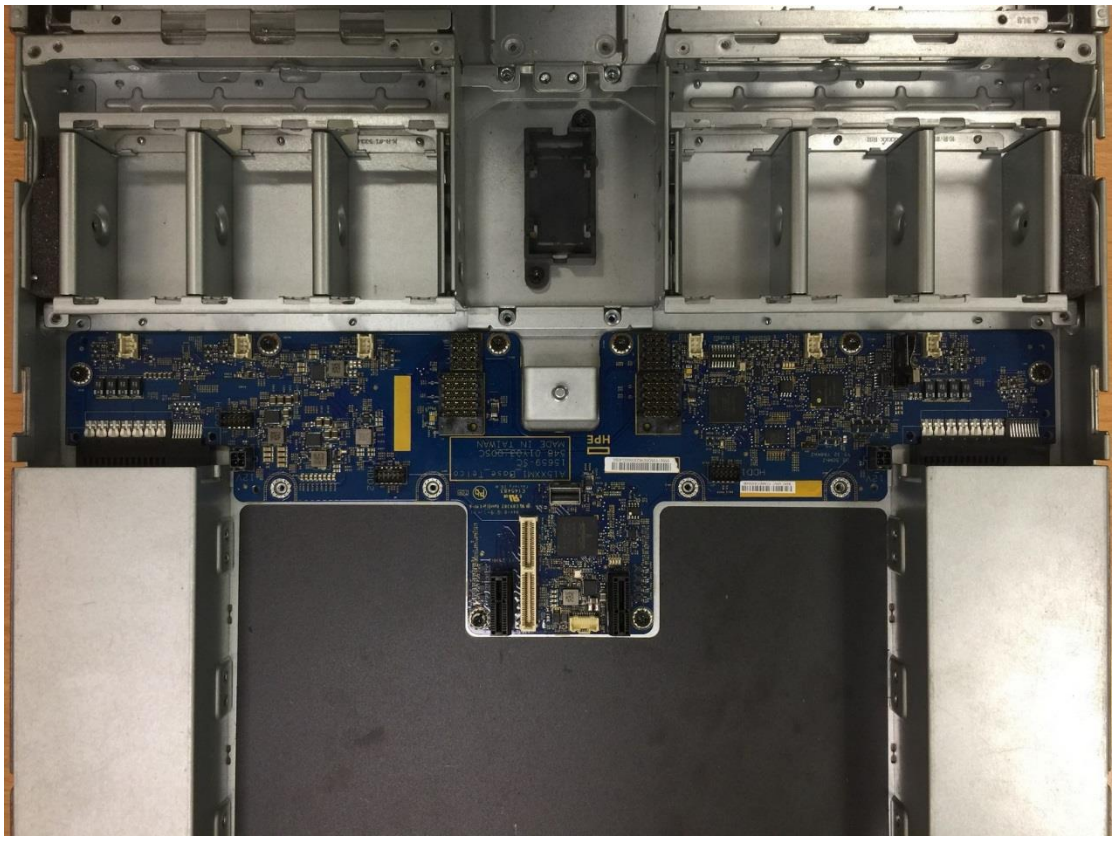
Release screws on front bezel module by T10 screw driver (totally 4pcs as red remark show)





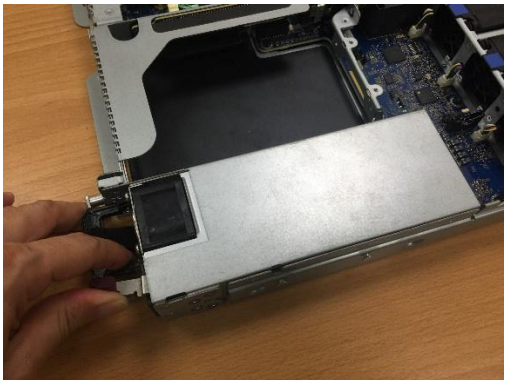
Pull-out the front bezel left side first and the other side to remove the front bezel after removing all screws.

Remove the main board



Loosen the main board by T15 screw driver (totally 8pcs as red mark show). Take out the main board to remove from chassis after loosening screws

Remove rear left and rear right PSU module



Press the latch on PSU module and pull-out the PSU module